Session: TU1D

Hybrid MCM Techniques and Applications

Chair

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Advances in hybrid MCM (multichip module) techniques involve the application of various high-density interconnect technologies. In this session, methods for forming antennas and other circuits in multi-layer substrates are discussed along with techniques for vertical interconection of microwave signals within such structures. In addition, advances in transmission lines and other hybrid circuit elements are discussed.

8:00 am - 9:50 am Tuesday, June 18, 1996
Room 134